

2SK3419

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1099-0200

(Previous: ADE-208-942)

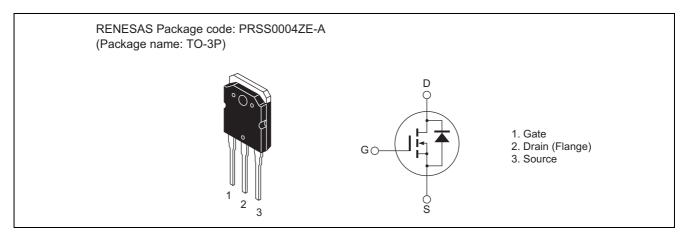
Rev.2.00

Sep 07, 2005

Features

- Low on-resistance $R_{DS (on)} = 4.3 \text{ m}\Omega \text{ typ.}$
- 4 V gate drive device
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	90	А
Drain peak current	I _{D (pulse)} Note 1	360	А
Body-drain diode reverse drain current	I _{DR}	90	А
Avalanche current	I _{AP} Note 3	65	А
Avalanche energy	E _{AR} Note 3	362	mJ
Channel dissipation	Pch Note 2	150	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \mu s$, duty cycle $\le 1\%$

2. Value at Tc = 25°C

3. Value at Tch = 25°C, Rg \geq 50 Ω

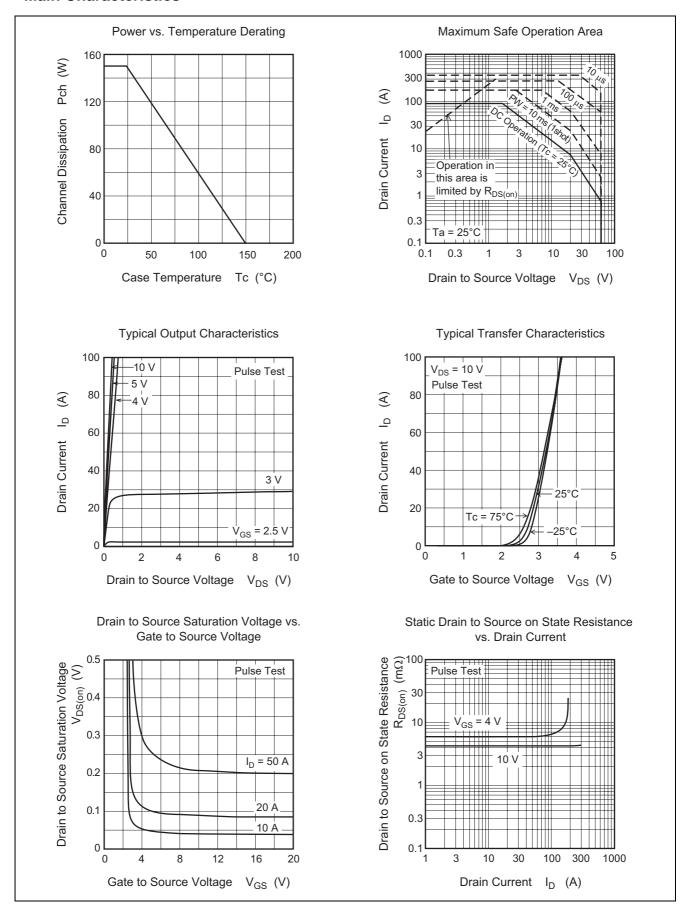
Electrical Characteristics

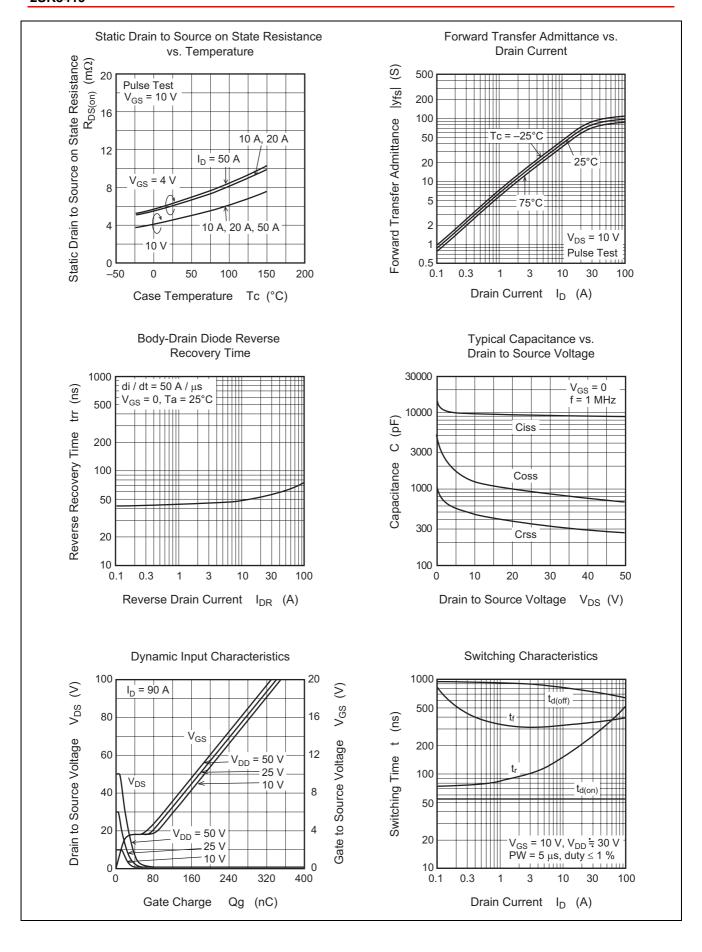
 $(Ta = 25^{\circ}C)$

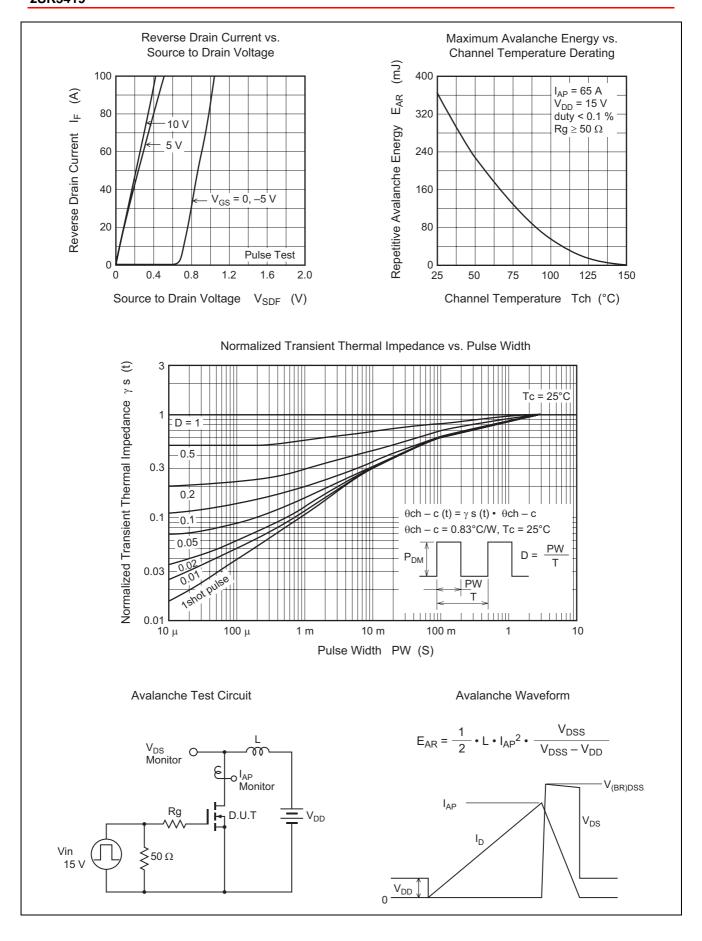
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	V _{DS} = 60 V, V _{GS} = 0
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	1.0	_	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}^{Note 4}$
Forward transfer admittance	y _{fs}	55	90	_	S	$I_D = 45 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Static drain to source on state resistance	R _{DS (on)}	_	4.3	5.5	mΩ	$I_D = 45 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	6.0	9.0	mΩ	I _D = 45 A, V _{GS} = 4 V Note 4
Input capacitance	Ciss	_	9770	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	1340	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	470	_	pF	f = 1 MHz
Total gate charge	Qg	_	180	_	nC	V _{DD} = 50 V
Gate to source charge	Qgs	_	32	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	36	_	nC	I _D = 90 A
Turn-on delay time	t _{d (on)}	_	53	_	ns	V _{GS} = 10 V
Rise time	t _r	_	320	_	ns	I _D = 45 A
Turn-off delay time	t _{d (off)}	_	700	_	ns	$R_L = 0.67 \Omega$
Fall time	t _f	_	380		ns	
Body-drain diode forward voltage	V_{DF}	_	1.0		V	I _F = 90 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	_	75	_	ns	$I_F = 90 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

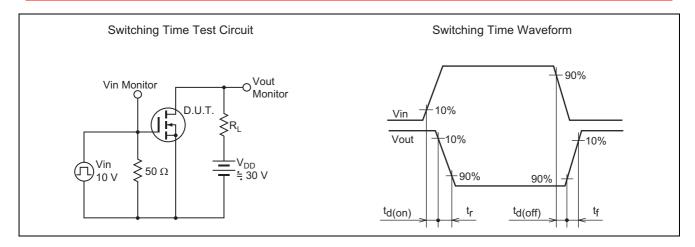
Note: 4. Pulse test

Main Characteristics

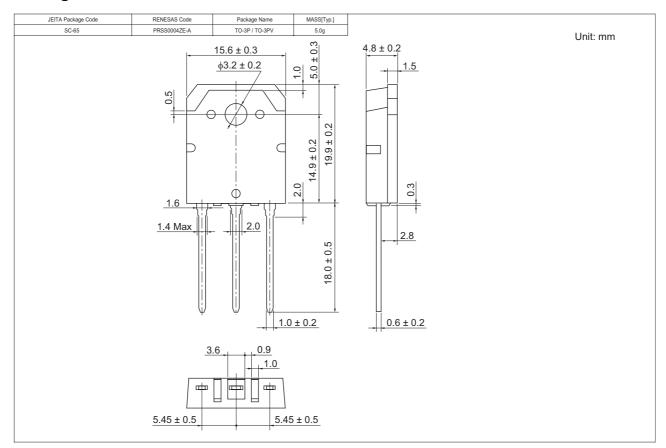








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK3419-E	30 pcs	Plastic magazine

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